

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	4925	(dicing or diced or singulation or singulating or cleaving or cleaved or cleavage or scribe or scribing or scribed) same (measur\$3 or determin\$5 or calculat\$3 or decision or deciding or configur\$5 or detect\$3) near4 (size or shape or width or length)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 13:31
S2	1196	(dicing or diced or singulation or singulating or cleaving or cleaved or cleavage or scribe or scribing or scribed) near10 (measur\$3 or determin\$5 or calculat\$3 or decision or deciding or configur\$5 or detect\$3) near2 (size or shape or width or length)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 10:13
S3	12	(dicing or diced or singulation or singulating or cleaving or cleaved or cleavage or scribe or scribing or scribed) near10 (measur\$3 or determin\$5 or calculat\$3 or decision or deciding or configur\$5 or detect\$3) near2 (size or shape or width or length) same (computer or database)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 10:25
S4	7	("5305222" "5444538" "5459340" "5654792" "5699260" "5874189" "6064759").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/05 10:18
S5	27	(dicing or diced or singulation or singulating or cleaving or cleaved or cleavage or scribe or scribing or scribed) near10 (size or shape or width or length) near10 (computer or database or control near system or controller)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 10:33
S6	61	(chip or die or ic or circuit or semiconductor or silicon) near6 (dicing or diced or singulation or singulating or cleaving or cleaved or cleavage or scribe or scribing or scribed) near6 (computer or database or control near system or controller)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 11:07
S7	1212	(ic or integrated adj circuit or die or chip) near5 (back near end or end near line or back near line)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 11:08
S8	182	(ic or integrated adj circuit or die or chip) near5 (back near end or end near line or back near line) and (bonding or bonded or attachment or flip adj chip or attaching or adhering) and (plasma or cure or curing or anneal or annealing or cured or annealed)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 11:14
S9	11098	(ic or integrated adj circuit or die or chip) near5 (packaging or package or assembly or dicing or sawing or singulating or singulation or diced or sawed or cleaving or scribing) near4 (system or apparatus or machine)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 11:15
S10	3261	(ic or integrated adj circuit or die or chip) near5 (packaging or package or assembly or dicing or sawing or singulating or singulation or diced or sawed or cleaving or scribing) near4 (system or apparatus or machine) and (attachment or attaching or flip adj chip or bonding or bonded or adhering) and (cure or curing or thermal or plasma or anneal or annealing or cured or annealed)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 11:21
S11	1099	(ic or integrated adj circuit or die or chip) near2 (packaging or package or assembly or back adj end or line or "in-line" or back near line) near2 (system or apparatus or machine) and (attachment or attaching or flip adj chip or bonding or bonded or adhering) and (cure or curing or thermal or plasma or anneal or annealing or cured or annealed)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 11:24

S12	102	(ic or integrated adj circuit or die or chip) near2 (packaging or package or assembly or back adj end or line or "in-line" or back near line) near2 (system or apparatus or machine) and (attachment or attaching or flip adj chip or bonding or bonded or adhering) same (cure or curing or thermal or plasma or anneal or annealing or cured or annealed) and (singulating or singulation or singulated or cutting or cut or sawing or sawed or dicing or diced or cleaving or cleavage or cleaved) same (test or testing or tested or sorting or sorted or sorter or sort)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 15:57
S13	6	("4960485" "5871610" "6080931" "6188127" "6223800" "6742561").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/05 11:49
S14	957	(ic or integrated adj circuit or die or chip) near2 (line) near2 (packaging or package or assembly)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 15:58
S15	72	(ic or integrated adj circuit or die or chip) near2 (line) near2 (packaging or package or assembly or assembling or manufacturing or manufacture) same (dicing or diced or singulation or singulated or singulating or cleaved or cleavage or cleaving or scribing or scribed or scribe or cutting or separating or separation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 16:31
S16	2203	(ic or integrated adj circuit or die or chip) near2 (packaging or package or assembly or assembling) near5 (pipeline or assembly adj line or pipe adj line or die adj strip or (chip or die) near2 array)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 16:32
S17	90	(ic or integrated adj circuit or die or chip) near2 (packaging or package or assembly or assembling) near5 (pipeline or assembly adj line or pipe adj line or die adj strip or (chip or die) near2 array) same (automated or automation or automating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 09:23
S18	47	(ic or integrated adj circuit or die or chip) near2 (packaging or package or assembly or assembling) near10 (pipeline or assembly adj line or pipe adj line or die adj strip or (chip or die) near2 array) near10 (automated or automation or automating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 16:33
S19	1	("6173750").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/05 16:48
S20	4	("5173766" "5541524" "5851664" "6566745").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/05 16:48
S21	206	(automatic or automated or automating or robotic) near4 (packaging or package or assembly) same (die or chip or ic) near3 (attaching or attach or attached or bonding or bonded or bond) same (wirebonding or wirebond or wire near bonding or wire near bonded or wirebonded or wire near bond)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 09:25
S22	36	("20020175153" "3387365" "3961413" "3982317" "4100675" "4219926" "4252864" "4316320" "4343083" "4480150" "4567643" "4663650" "4667403" "5023202" "5066614" "5352633" "5357674" "5366933" "5535509" "5620927" "5637916" "5765277" "5802709" "5852870" "5854741" "5897334" "5951804" "5953216" "5960961" "5987722" "5990545" "6001671" "6013946" "6049972" "6408510").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/06 10:58
S23	1	(in-line or inline) same (die or chip or ic) near3 (bonding or bond or attaching or attachment or attach or attached or flip or adhered or affixed) same (wirebond or wire adj bond or wirebonding or wire adj bonding or wirebonder or wire adj bonder) same (dicing or diced or singulation or singulating or singulated or cleaving or cleaved or cleaver or cleavage or sawing or cutting or separating or scribing) same (encapsulant or encapsulating or encapsulated or molding or molded)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/08 16:34

S24	658	(in-line or inline) and (die or chip or ic) near3 (bonding or bond or attaching or attachment or attach or attached or flip or adhered or affixed) and (wirebond or wire adj bond or wirebonding or wire adj bonding or wirebonder or wire adj bonder) and (dicing or diced or singulation or singulating or singulated or cleaving or cleaved or cleaver or cleavage or sawing or cutting or separating or scribing) and (encapsulant or encapsulating or encapsulated or molding or molded)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/08 16:39
S25	47	(in-line or inline) near4 (assembly or attach or fabrication or processing) and (die or chip or ic) near3 (bonding or bond or attaching or attachment or attach or attached or flip or adhered or affixed) and (wirebond or wire adj bond or wirebonding or wire adj bonding or wirebonder or wire adj bonder) and (dicing or diced or singulation or singulating or singulated or cleaving or cleaved or cleaver or cleavage or sawing or cutting or separating or scribing) and (encapsulant or encapsulating or encapsulated or molding or molded)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/08 16:40
S26	1052	(back-of-line or end-of-line or back-end) near2 (assembly or assembling or processing or packaging)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/12 16:16
S27	92	(back-of-line or end-of-line or back-end) near2 (assembly or assembling or processing or packaging) and (die or chip or wafer or device or ic) near2 (tape or strip or array)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/12 16:23
S28	2	"5782859".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/12 17:15
S29	39	(inline or in-line or back-end or front-end or back-of-line or front-of-line or automated or automatic or automation) same (die or chip or ic) near4 (attach\$4 or bond\$4 or flip or mount\$4 or adher\$4) same (cure or curing or anneal or annealing or annealed or cured or thermal or heat or heating or heated) same (wirebond\$3 or wire-bond\$3 or ball near2 (attach\$4 or bond\$3) or encapsulat\$3 or molding) same (singulation or singulating or singulated or dicing or diced or cleaving or cleaved or cleave or cleavage or cutting or separating or separation or scribing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 10:05
S30	39	(inline or in-line or back-end or front-end or back-of-line or front-of-line or automated or automatic or automation or computerized or robotic or computer near2 control\$4) same (die or chip or ic) near4 (attach\$4 or bond\$4 or flip or mount\$4 or adher\$4) same (cure or curing or anneal or annealing or annealed or cured or thermal or heat or heating or heated) same (wirebond\$3 or wire-bond\$3 or ball near2 (attach\$4 or bond\$3) or encapsulat\$3 or molding) same (singulation or singulating or singulated or dicing or diced or cleaving or cleaved or cleave or cleavage or cutting or separating or separation or scribing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 14:34
S31	1	(die or chip or ic) near3 (size or shape or dimension or length or width) near3 (independent\$3 or independence or universal\$2) near6 (singulation or singulating or singulated or cleaved or cleaving or cleavage or cleave or dicing or diced or separation or separating or cutting or scribing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 10:24
S32	30	(die or chip or ic or array or matrix or strip or package or housing) near4 (size or shape or dimension or length or width) near4 (independent\$3 or independence or universal\$2) near15 (singulation or singulating or singulated or cleaved or cleaving or cleavage or cleave or dicing or diced or separation or separating or cutting or scribing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 10:31

S33	8716	(die or chip or ic) near3 (strip or array or panel or tape or reel) same (assembly or assembling or packaging or packaged or assembled)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 10:32
S34	298	(die or chip or ic) near3 (strip or array or panel or tape or reel) near15 (assembly or assembling or packaging or packaged or assembled) near15 (automated or automatic or robotic or computerized or in-line or inline)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 10:32
S35	15	(US-20020079120-\$ or US-20020177875-\$ or US-20040005090-\$ or US-20040024551-\$).did. or (US-3387365-\$ or US-3814895-\$ or US-5366933-\$ or US-5915231-\$ or US-6445060-\$ or US-6465743-\$ or US-6489557-\$ or US-6529790-\$ or US-6574858-\$).did. or (JP-06224293-\$ or JP-57167657-\$).did.	US-PGPUB; USPAT; JPO	OR	ON	2005/04/13 11:37
S36	100	(automated or automatic or robotic) near2 (chip or die or ic) near3 (conveyor or conveying or conveyance or movement or mover or moving or transfer or transferring or transferral)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 13:32
S37	250	(automated or automatic or robotic) near2 (chip or die or ic) near3 (conveyor or conveying or conveyance or movement or mover or moving or transfer or transferring or transferral or handling or handler)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 14:32
S38	29	("4301958").URPN.	USPAT	OR	ON	2005/04/13 14:04
S39	124	(automated or automatic or robotic or computer\$5) near2 (chip or die or ic or package) near3 (dicing or diced or singulating or singulation or singulated or cleaving or cleaved or cleaver or scribing or cutting)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 14:36
S40	2	(automated or automatic or robotic) near2 (chip or die or ic) near3 (conveyor or conveying or conveyance or movement or mover or moving or transfer or transferring or transferral or handling or handler or assembler or assembly or assembling) and (size or length or width) near2 (independent or independence or universal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 14:33
S41	0	(pipeline or pipe-line) same (die or chip or ic) near4 (attach\$4 or bond\$4 or flip or mount\$4 or adhere\$4) same (cure or curing or anneal or annealing or annealed or cured or thermal or heat or heating or heated) same (wirebond\$3 or wire-bond\$3 or ball near2 (attach\$4 or bond\$3) or encapsulat\$3 or molding) same (singulation or singulating or singulated or dicing or diced or cleaving or cleaved or cleave or cleavage or cutting or separating or separation or scribing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 14:35
S42	73	(pipeline or pipe-line) same (die or chip or ic) near4 (attach\$4 or bond\$4 or flip or mount\$4 or adhere\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 14:35
S43	871	(automated or automatic or robotic or computer\$5) near2 (chip or die or ic or package) near3 (testing or test or tested or inspection or inspecting or inspected or sorting or sorted)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 14:38
S44	293	(automated or automatic or robotic or computer\$5) near2 (chip or die or ic or package) near3 (testing or test or tested or inspection or inspecting or inspected or sorting or sorted) and (chip or die or ic or package) near3 (assembly or assembling or packaging or packaged or attach or attaching or attachment or mounting or mounted)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 14:39

S45	195	(automated or automatic or robotic or computer\$5) near2 (chip or die or ic or package) near3 (testing or test or tested or inspection or inspecting or inspected or sorting or sorted) and (chip or die or ic or package) near3 (assembly or assembling or packaging or packaged or attach or attaching or attachment or mounting or mounted) and (sort or sorting or sorted or reject or rejecting or failure or failing or failed or rejected)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 14:57
S46	669	(chip or die or ic or package) near3 (assembly or assembling or packaging or packaged or attach or attaching or attachment or mounting or mounted) and (wirebond\$3 or wire adj bond\$3) and (ball or solder or bump) near2 (attach\$4 or affix\$3 or mount\$3) and (encapsulat\$3 or encapsulant or molding or molded or molder) and (singulation or singulating or cutting or cutter or singulater or singulated or cleaving or cleaver or cleaved or cleavage or separation or separator or dicing or diced) and (anneal or annealing or annealer or thermal or heat or heating or heater or curing or cured or cure) and (clean or cleaning or cleaner or plasma or ashing or asher)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 15:04
S47	430	(chip or die or ic or package) near3 (assembly or assembling or packaging or packaged or attach or attaching or attachment or mounting or mounted) and (wirebond\$3 or wire adj bond\$3) and (ball or solder or bump) near2 (attach\$4 or affix\$3 or mount\$3) and (encapsulat\$3 or encapsulant or molding or molded or molder) and (singulation or singulating or cutting or cutter or singulater or singulated or cleaving or cleaver or cleaved or cleavage or separation or separator or dicing or diced) and (anneal or annealing or annealer or thermal or heat or heating or heater or curing or cured or cure) and (clean or cleaning or cleaner or plasma or ashing or asher) and (test or testing or tester or tested or inspection or inspecting or inspected)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 15:05
S48	14	(chip or die or ic or package) near3 (assembly or assembling or packaging or packaged or attach or attaching or attachment or mounting or mounted) and (wirebond\$3 or wire adj bond\$3) and (ball or solder or bump) near2 (attach\$4 or affix\$3 or mount\$3) and (encapsulat\$3 or encapsulant or molding or molded or molder) and (singulation or singulating or cutting or cutter or singulater or singulated or cleaving or cleaver or cleaved or cleavage or separation or separator or dicing or diced or sawing or sawed) and (anneal or annealing or annealer or thermal or heat or heating or heater or curing or cured or cure) and (clean or cleaning or cleaner or plasma or ashing or asher) and (test or testing or tester or tested or inspection or inspecting or inspected) and (sorting or sorter or sorted or (rejecting or rejection or failure or failed or reject or failing or rejected) near2 (bin or disposing or disposal or removing or removal))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 15:10
S49	109	(chip or die or ic or package) near3 (assembly or assembling or packaging or packaged or attach or attaching or attachment or mounting or mounted) and (wirebond\$3 or wire adj bond\$3) and (ball or solder or bump) near2 (attach\$4 or affix\$3 or mount\$3) and (encapsulat\$3 or encapsulant or molding or molded or molder) and (singulation or singulating or cutting or cutter or singulater or singulated or cleaving or cleaver or cleaved or cleavage or separation or separator or dicing or diced or sawing or sawed) and (anneal or annealing or annealer or thermal or heat or heating or heater or curing or cured or cure) and (clean or cleaning or cleaner or plasma or ashing or asher) and (test or testing or tester or tested or inspection or inspecting or inspected) and (ic or package or finished or die or chip) near4 (tape or reel)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 15:10
S50	29	(bga or pcb) near4 (automated or automatic or robotic or in-line or inline or front-of-line or front-end) near4 (die or chip or ic) near4 (attach\$4 or bond\$3 or affix\$3 or adher\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/14 10:50
S51	6	(chip or die or ic or package) near3 (assembly or assembling or packaging or packaged or attach or attaching or attachment or mounting or mounted) and (ball or bga) near2 (attach\$4 or affix\$3 or adher\$3 or disposing) near10 (copper and plastic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/14 11:35

S52	1287	polyimide near plastic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/14 11:35
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